Special Issue

Advanced Packaging Technology for MEMS Devices

Message from the Guest Editor

Advanced packaging technology for MEMS devices is crucial for their successful commercialization and performance. Advanced packaging is important for MEMS devices because it ensures the reliability and longevity of these devices. Moreover, the growing advanced packaging technology also enables increasing system integration and sensor fusion. Under advanced packaging, several technology clusters are developing simultaneously. Wafer-level-packaging (WLP) integrates the MEMS device and packaging at the wafer level, allowing the highest integration grade and cost efficiency. In addition, more and more new chip-level packaging technologies and materials have been investigated and drawing attention for advanced packaging technologies, which allows higher system flexibility. The various technology clusters are gaining increasing importance in modern electronics and sensor applications.

Guest Editor

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